

06-01-1998

MRD 5-26-98

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To the Hon. Commissioner of Patents &amp; Trademarks: Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies):</p> <p>Takuo FUNAYA and Koji MATSUI</p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>2. Name and address of receiving party(ies):</p> <p>Name: NEC CORPORATION</p> <p>Street Address: 7-1, Shiba 5-chome Minato-ku Tokyo, Japan</p>
<p>3. Nature of conveyance:</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger</p> <p><input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name</p> <p><input type="checkbox"/> Other</p> <p>Execution Date: May 25, 1998</p>	<p>4. Application number(s) or patent (number(s):</p> <p>If this document is being filed together with a new application, the execution date of the application is: May 25, 1998</p> <p>A. Patent Application No(s).</p> <p>B. Patent No(s).</p> <p>Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>YOUNG &amp; THOMPSON Second Floor 745 South 23rd Street Arlington, VA 22202</p>	<p>6. Total number of applications and patents involved:</p> <p style="text-align: center;"><b>One</b></p> <p>7. Total fee (37 CFR 3.41).....\$ <b>40</b></p> <p><input checked="" type="checkbox"/> Enclosed</p> <p><input type="checkbox"/> Authorized to be charged to deposit account</p> <p>8. Deposit Account No. <b>25-0120</b></p> <p>(Attach duplicate copy of this page if paying by deposit account)</p>

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## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Lauren Terry  
Name of Person Signing

*Lauren Terry*  
Signature

May 26, 1998  
Date

Total number of pages including cover sheet: **[2]**

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40.00 DP

PATENT  
REEL: 9192 FRAME: 0277

**ASSIGNMENT**

WHEREAS, Takuo FUNAYA and Koji MATSUI of Tokyo, Japan,  
hereafter referred to as applicants, have invented certain new and useful  
improvements in SUPPORTING SUBSTRATE TO BE BONDED WITH SEMICONDUCTOR  
BARE CHIP AND METHOD OF THERMOCOMPRESSSION-BONDING THE SAME,

(a) for which an application for a United States Patent was filed on  
May 25, 1998, Application No. \_\_\_\_\_,


(b) for which an application for a United States Patent was executed on  
\_\_\_\_\_, and

WHEREAS, **NEC CORPORATION**, of 7-1, Shiba 5-chome, Minato-  
ku, Tokyo, Japan, hereinafter referred to as "assignee" is desirous of acquiring  
the entire right, title and interest in the same;


NOW, THEREFORE, in consideration of the sum of Ten Dollars  
(\$10.00), the receipt whereof is acknowledged, and other good and valuable  
consideration, we, the applicants, by these presents do\_\_ sell, assign and  
transfer unto said assignee the full and exclusive right to the said invention in  
the United States and the entire right, title and interest in and to any and all  
Patents which may be granted therefor in the United States.

We hereby authorize and request the Commissioner of Patents  
& Trademarks to issue said United States Patent to said assignee, of the entire  
right, title and interest in and to the same, for its sole use and behoof; and for  
the use and behoof of its legal representatives, to the full end of the term for  
which said Patent may be granted, as fully and entirely as the same would  
have been held by us had this assignment and sale not been made.

Date: May 25, 1998

Takuo Funaya   
Takuo FUNAYA

Date: May 25, 1998

Koji Matsui   
Koji MATSUI

Witness:

Masazumi Takeuchi Shinji Matsui